

IN THE SPECIFICATION

Please replace the paragraph beginning at page 5, line 24 to page 6, line 6, with the following rewritten paragraph:

Further, a high thermal conductive aluminum nitride sintered body according to a second invention is characterized in that the high thermal conductive aluminum nitride sintered body has a thermal conductivity of $200 \text{ W/m} \cdot \text{K}$ or more; and a three point bending strength of 250 MPa or more; wherein a ratio ($I_{\text{Al}_2\text{Y}_4\text{O}_9}/I_{\text{AlN}}$) of X-ray diffraction intensity ($I_{\text{Al}_2\text{Y}_4\text{O}_9}$) of $\text{Al}_2\text{Y}_4\text{O}_9$ ~~aluminum nitride~~ (201 plane) with respect to X-ray diffraction intensity (I_{AlN}) of AlN (101 plane) is 0.002 to 0.06, and a ratio ($I_{\text{Y}_2\text{O}_3}/I_{\text{AlN}}$) of X-ray diffraction intensity ($I_{\text{Y}_2\text{O}_3}$) of Y_2O_3 (222 plane) with respect to X-ray diffraction intensity (I_{AlN}) of AlN (101 plane) is 0.008 to 0.06.

Please replace the paragraph at page 11, lines 11-21, with the following rewritten paragraph:

When the above average grain size or the minimum size of the aluminum nitride crystal grains is less than the above lower limit, the number of grain boundary phases that become heat resistance is increased thereby to easily lower the thermal conductivity. On the other hand, when the above ~~minimum~~ maximum size of the aluminum nitride crystal grains exceeds the above upper limit, the structural strength of the sintered body is lowered, although the thermal conductivity is increased. Further, when the number of the aluminum nitride crystal grains existing in predetermined area exceeds the above upper limit, the number of grain boundary phases that become heat resistance is increased thereby to lower the thermal conductivity of the sintered body, although the structural strength is increased.

Please replace the paragraph beginning at page 19, line 26 to page 20, line 5, with the following rewritten paragraph:

Each of the aluminum nitride sintered bodies manufactured in accordance with the above method has a high thermal conductivity of $220\text{W/m} \cdot \text{K}$ (at 25°C) or greater, preferably $250\text{W/m} \cdot \text{K}$ or greater, as a poly crystalline body, and has a three point bending strength of 200 MPa or greater, preferably $[[200]]$ 240 MPa or greater, thus being excellent in mechanical characteristics.